

N+P Channel Enhancement Mode MOSFET

1. Product Information

1.1 Features

- ☒ Surface-mounted package
- ☒ Advanced trench cell design
- ☒ Excellent $R_{DS(ON)}$
- ☒ Low gate charge

1.2 Applications

- ☒ PWM applications
- ☒ Load switch

1.3 Quick reference

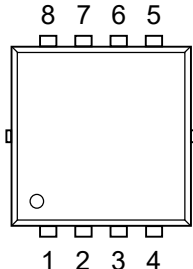
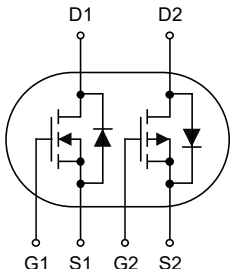
• N-Channel

- ☒ $BV \geq 20\text{ V}$
- ☒ $R_{DS(ON)} \leq 10\text{ m}\Omega @V_{GS} = 4.5\text{ V}$
- ☒ $I_D \leq 10\text{ A}$
- ☒ $R_{DS(ON)} \leq 16\text{ m}\Omega @V_{GS} = 2.5\text{ V}$

• P-Channel

- ☒ $BV \leq -20\text{ V}$
- ☒ $R_{DS(ON)} \leq 26\text{ m}\Omega @V_{GS} = -4.5\text{ V}$
- ☒ $I_D \geq -8\text{ A}$
- ☒ $R_{DS(ON)} \leq 37\text{ m}\Omega @V_{GS} = -2.5\text{ V}$

2. Pin Description

Pin	Description	Simplified Outline	Symbol
1	Source (S2)	 Top View PDFN3.3x3.3-8L	
2	Gate (G2)		
3	Source (S1)		
4	Gate (G1)		
5,6	Drain (D1)		
7,8	Drain (D2)		

3. Limiting Values

Symbol	Parameter	Conditions	Limit	Unit
• N-Channel				
V_{DS}	Drain-Source Voltage	$T_A=25^{\circ}\text{C}$	20	V
V_{GS}	Gate-Source Voltage	$T_A=25^{\circ}\text{C}$	± 12	V
I_D^*	Drain Current	$T_A=25^{\circ}\text{C}$	10	A
		$T_A=70^{\circ}\text{C}$	8	A
$I_{DM}^{*,**}$	Pulsed Drain Current	$T_A=25^{\circ}\text{C}$	40	A
• P-Channel				
V_{DS}	Drain-Source Voltage	$T_A=25^{\circ}\text{C}$	-20	V
V_{GS}	Gate-Source Voltage	$T_A=25^{\circ}\text{C}$	± 12	V
I_D^*	Drain Current	$T_A=25^{\circ}\text{C}$	-8	A
		$T_A=70^{\circ}\text{C}$	-6.4	A
$I_{DM}^{*,**}$	Pulsed Drain Current	$T_A=25^{\circ}\text{C}$	-32	A
P_{tot}	Total Power Dissipation	$T_A=25^{\circ}\text{C}$	4	W
T_J, T_{stg}	Operating Junction and Storage Temperature Range		-55~150	$^{\circ}\text{C}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case		31.3	$^{\circ}\text{C/W}$

Notes:

* Surface mounted on 1 in² pad area, $t \leq 10$ sec.

** Pulse width ≤ 300 μs , duty cycle $\leq 1\%$.

4. Marking Information

Product Name	Marking
KJ4602QD	4602QD XXXX

5. Ordering Code

Product Name	Package	Reel size	Tape width	Quantity (pcs)
KJ4602QD	PDFN 3.3x3.3-8L	13"	12 mm	5000

Note: KJ4602QD defines "Green" as lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC/JEDEC J-STD-020C).

6. Electrical Characteristics (T_A=25°C unless otherwise noted)

• N-Channel

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0 V, I _D =250 μA	20	-	-	V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250 μA	0.4	0.7	1.0	V
I _{DSS}	Drain Leakage Current	V _{DS} =20 V, V _{GS} =0 V	-	-	1	μA
I _{GSS}	Gate Leakage Current	V _{GS} =±12 V, V _{DS} =0 V	-	-	±100	nA
R _{DS(ON)} ^a	Drain-Source On-State Resistance	V _{GS} =4.5 V, I _D =10 A	-	8	10	mΩ
		V _{GS} =2.5 V, I _D =7 A	-	12	16	
g _{fs}	Forward transconductance	V _{DS} =5 V, I _D =5 A	-	5	-	S
Dynamic Characteristics ^b						
C _{iss}	Input Capacitance	V _{GS} =0 V, V _{DS} =10 V, f=1 MHz	-	1255	-	pF
C _{oss}	Output Capacitance		-	225	-	
C _{rss}	Reverse Transfer Capacitance		-	165	-	
t _{d(on)}	Turn-on Delay Time	V _{DS} =10 V, V _{GEN} =4.5 V, R _G =50 Ω, I _D =5 A	-	6.5	-	ns
t _r	Turn-on Rise Time		-	8.6	-	
t _{d(off)}	Turn-off Delay Time		-	70	-	
t _f	Turn-off Fall Time		-	45	-	
Gate Charge Characteristics ^b						
Q _g	Total Gate Charge	V _{DS} =10 V, V _{GS} =4.5 V, I _{DS} =10 A	-	28	-	nC
Q _{gs}	Gate-Source Charge		-	5.5	-	
Q _{gd}	Gate-Drain Charge		-	6.3	-	
Diode Characteristics						
V _{SD} ^a	Diode Forward Voltage	I _{SD} =1 A, V _{GS} =0 V	-	0.75	1.2	V

Notes:

a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.

b. Guaranteed by design, not subject to production testing.

7. Electrical Characteristics (T_A=25°C unless otherwise noted)

• P-Channel

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0 V, I _{DS} =-250 μA	-20	-	-	V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =-250 μA	-0.45	-0.7	-1.0	V
I _{DSS}	Drain Leakage Current	V _{DS} =-20 V, V _{GS} =0 V	-	-	-1.0	μA
I _{GSS}	Gate Leakage Current	V _{DS} =0 V, V _{GS} =±12 V	-	-	±100	nA
R _{DS(ON)} ^a	On-State Resistance	V _{GS} =-4.5 V, I _{DS} =-8 A	-	17	26	mΩ
		V _{GS} =-2.5 V, I _{DS} =-5 A	-	22	37	
g _{fs}	Forward transconductance	V _{DS} =-5 V, I _D =-8 A	-	5	-	S
Dynamic Characteristics ^b						
C _{iss}	Input Capacitance	V _{GS} =0 V, V _{DS} =-4.5 V f=1 MHz	-	1200	-	pF
C _{oss}	Output Capacitance		-	195	-	
C _{rss}	Reverse Transfer Capacitance		-	170	-	
t _{d(on)}	Turn-on Delay Time	V _{DS} =-10 V, V _{GEN} =-4.5 V, R _G =10 Ω, I _{DS} =-5 A	-	11	-	ns
t _r	Turn-on Rise Time		-	35	-	
t _{d(off)}	Turn-off Delay Time		-	30	-	
t _f	Turn-off Fall Time		-	10	-	
Gate Charge Characteristics ^b						
Q _g	Total Gate Charge	V _{DS} =-10 V, V _{GS} =-4.5 V, I _{DS} =-5 A	-	34	-	nC
Q _{gs}	Gate-Source Charge		-	3.8	-	
Q _{gd}	Gate-Drain Charge		-	10.4	-	
Diode Characteristics						
V _{SD} ^a	Diode Forward Voltage	I _{SD} =-1 A, V _{GS} =0 V	-	-0.78	-1.3	V

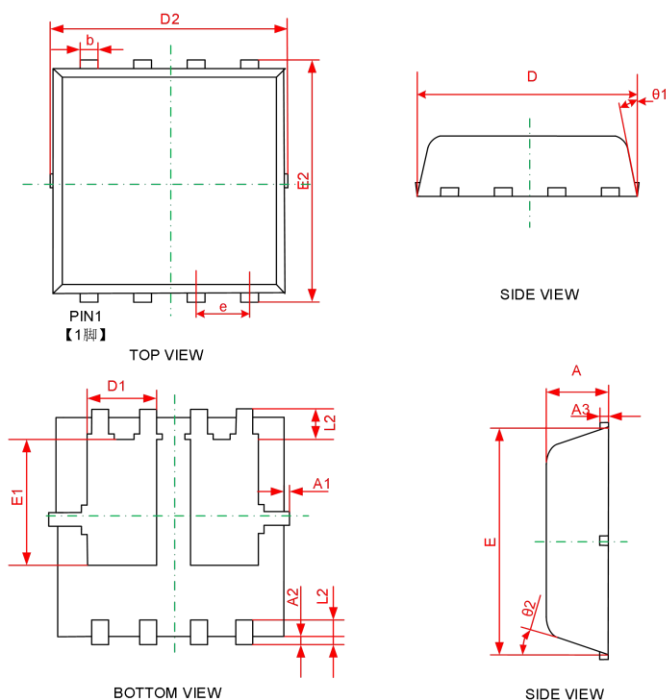
Notes:

a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.

b. Guaranteed by design, not subject to production testing.

8. Package Dimensions

PDFN3.3x3.3-8L (Dual) package



Symbol	Dimensions in Millimeters	
	Min	Max
A	0.750	0.850
A1	0.000	0.050
A2	0.100	0.200
A3	0.152 REF.	
b	0.200	0.400
D	3.050	3.250
D1	0.935	1.135
D2	3.200	3.400
E	2.900	3.100
E1	1.635	1.835
E2	3.150	3.350
e	0.625	0.675
L1	0.350	0.450
L2	0.365	0.465
θ1	10°	12°
θ2	10°	12°